7GHz, 1:2 CML FANOUT BUFFER/TRANSLATOR WITH INTERNAL I/O TERMINATION

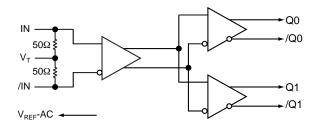
FEATURES

- Precision 1:2, 400mV CML fanout buffer
- Guaranteed AC performance over temperature/ voltage:
 - >7GHz f_{MAX} clock
 - < 60ps t_r / t_f times
 - < 250ps t_{pd}
 - < 15ps max. skew
- Low jitter performance:
 - < 10ps_(pk-pk) total jitter (clock)
 - < 1ps_(rms) random jitter (data)
 - < 10ps_(pk-pk) deterministic jitter (data)
- Accepts an input signal as low as 100mV
- Unique input termination and V_T pin accepts DC-coupled and AC-coupled differential inputs: LVPECL, LVDS, and CML
- 50 Ω source terminated CML outputs
- Power supply 2.5V ±5% and 3.3V ±10%
- Industrial temperature range: -40°C to +85°C
- Available in 16-pin (3mm × 3mm) MLFTM package

APPLICATIONS

- All SONET and GigE clock distribution
- Fibre Channel clock and data distribution
- Backplanes
- Data distribution: OC-48, OC-48+FEC, XAUI
- High-end, low skew, multiprocessor synchronous clock distribution

FUNCTIONAL BLOCK DIAGRAM



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Precision Edge™

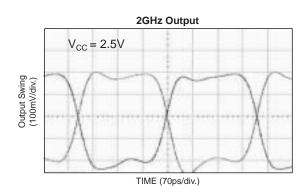
DESCRIPTION

The SY58011U is a 2.5V/3.3V precision, high-speed, fully differential 1:2 CML fanout buffer. Optimized to provide two identical output copies with less than 15ps of skew and less than $10ps_{(pk-pk)}$ total jitter, the SY58011U can process clock signals as fast as 7GHz or data patterns up to 10.7Gbps.

The differential input includes Micrel's unique, 3-pin input termination architecture that interfaces to LVPECL, LVDS, or CML differential signals, (AC-coupled or DC-coupled) as small as 100mV without any level-shifting or termination resistor networks in the signal path. For AC-coupled input interface applications, an on-board output reference voltage (V_{REF}-AC) is provided to bias the V_T pin. The outputs are compatible with 400mV typical swing into 50Ω loads, with extremely fast rise/fall times guaranteed to be less than 60ps.

The SY58011U operates from a 2.5V ±5% supply or 3.3V ±10% supply and is guaranteed over the full industrial temperature range (−40°C to +85°C). For applications that require LVPECL outputs, consider the SY58012U or SY58013U 1:2 fanout buffer with 800mV and 400mV output swing, respectively. The SY58011U is part of Micrel's high-speed, Precision Edge[™] product line. Data sheets and support documentation can be found on Micrel's web site at www.micrel.com.

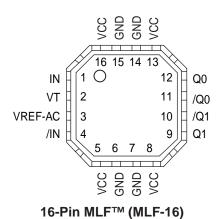
TYPICAL PERFORMANCE



2GHz with 100mV Input

Rev.: A Amendment: /0
Issue Date: July 2003

PACKAGE/ORDERING INFORMATION



Ordering Information(Note 1)

| Part Number | Package Type | Operating Range | Package Marking | |
|----------------------------------|-----------------|--------------------|--------------------|--|
| SY58011UMI | MLF-16 | Industrial | 011U | |
| SY58011UMITR ^(Note 2) | MLF-16 | Industrial | 011U | |

Note 1. Contact factory for die availability. Die are guaranteed at $T_A = 25^{\circ}C$, DC electricals only.

Note 2. Tape and Reel.

PIN DESCRIPTION

| Pin Number | Pin Name | Pin Function | |
|-----------------|-----------------------|--|--|
| 1, 4 | IN, /IN | Differential Input: This input pair is the signal to be buffered. Each pin of this pair internally terminates with 50Ω to the V_T pin. Note that this input will default to an indeterminate state if left open. See "Input Interface Applications" section. | |
| 2 | VT | Input Termination Center-Tap: Each input terminates to this pin. The V _T pin provides a center-tap for each input (IN, /IN) to a termination network for maximum interface flexibility. See <i>"Input Interface Applications"</i> section. | |
| 3 | VREF-AC | Reference Output Voltage: This output biases to V_{CC} –1.4V. It is used when AC-coupling the inputs (IN, /IN). Connect V_{REF} -AC directly to the V_{T} pin. Bypass with 0.01 μ F low ESR capacitor to V_{CC} . Maximum current source or sink is 0.5mA. See "Input Interface Applications" section. | |
| 5, 8, 13, 16 | VCC | Positive Power Supply: Bypass with $0.1\mu F//0.01\mu F$ low ESR capacitors as close to the V_{CC} pins as possible. | |
| 6, 7, 14, 15 | GND, (Exposed Pad) | Ground. Exposed pad must be connected to a ground plane that is the same potential as the ground pin. | |
| 12, 11 9, 10 | Q0, /Q0, Q1, /Q1 | CML Differential Output Pairs: Differential buffered output copy of the input signal. The output swing is typically 400mV. Unused output pairs may be left floating with no impact on jitter. See "CML Output Termination" section. | |

Absolute Maximum Ratings(Note 1)

| Power Supply Voltage (V $_{ m CC}$) –0.5V to +4.0V |
|--|
| Input Voltage (V _{IN}) |
| CML Output Voltage (V_{OUT}) V_{CC} -1.0V to V_{CC} +0.5V |
| Current (V _T) |
| Source or sink current on V _T pin±100mA |
| Input Current |
| Source or sink current on IN, /IN±50mA |
| Current (V _{REF}) |
| Source or sink current on V _{REF} -AC, Note 4 ±1.5mA |
| Lead Temperature Soldering, (10 seconds) 270°C |
| Storage Temperature Range (T _{STORE}) –65°C to +150°C |
| |

Operating Ratings(Note 2)

| Supply Voltage (V _{CC}) | . +2.375V to +3.60V |
|---|---------------------|
| Operating Temperature Range (T _A) | –40°C to +85°C |
| Package Thermal Resistance, Note 3 | |
| MLF™ (θ _{JA}) | |
| Still-Air | 60°C/W |
| 500lfpm | 54°C/W |
| MLF TM (ψ _{JB}) | 33°C/W |

DC ELECTRICAL CHARACTERISTICS(Note 5)

 $T_{\Delta} = -40^{\circ}\text{C} \text{ to } +85^{\circ}\text{C}$

| Symbol | Parameter | Condition | Min | Тур | Max | Units |
|----------------------|----------------------------------|--------------------------------|------------------------|----------------------|------------------------|-------|
| V_{CC} | Power Supply Voltage | | 2.375 | | 3.60 | V |
| I _{CC} | Power Supply Current | Max. V _{CC} , no load | | 75 | 95 | mA |
| V_{IH} | Input HIGH Voltage | IN, /IN, Note 6 | V _{CC} -1.6 | | V _{CC} | V |
| V_{IL} | Input LOW Voltage | IN, /IN | 0 | | V _{IH} -0.1 | V |
| V_{IN} | Input Voltage Swing | see Figure 1a. | 0.1 | | 1.7 | V |
| V _{DIFF_IN} | Differential Input Voltage Swing | see Figure 1b. | 0.2 | | 3.4 | V |
| R _{IN} | Into V _T Resistance | | 40 | 50 | 60 | Ω |
| V _{REF} -AC | Output Reference Voltage | | V _{CC} -1.525 | V _{CC} -1.4 | V _{CC} –1.325 | V |
| IN to V _T | | | | | 1.28 | V |

CML DC ELECTRICAL CHARACTERISTICS(Note 5)

 $V_{CC} = 3.3V \pm 10\%$ or 2.5V $\pm 5\%$; $T_A = -40^{\circ}C$ to $+85^{\circ}C$; $R_L = 100\Omega$ across each output pair, or equivalent, unless otherwise stated.

| Symbol | Parameter | Condition | | Тур | Max | Units |
|-----------------------|--------------------------------------|---------------------------------|------------------------|------------------------|----------|-------|
| V _{OH} | Output HIGH Voltage Q0, /Q0, Q1, /Q1 | | V _{CC} -0.020 | V _{CC} -0.010 | V_{CC} | V |
| V _{OUT} | Output Voltage Swing | Q0, /Q0, Q1, /Q1; see Figure 1a | 325 | 400 | | mV |
| V _{DIFF_OUT} | Differential Output Voltage Swing | Q0, /Q0, Q1, /Q1; see Figure 1b | 650 | 800 | | mV |
| R _{OUT} | Output Source Impedance | Q0, /Q0, Q1, /Q1 | 40 | 50 | 60 | Ω |

- Note 1. Permanent device damage may occur if ABSOLUTE MAXIMUM RATINGS are exceeded. This is a stress rating only and functional operation is not implied at conditions other than those detailed in the operational sections of this data sheet. Exposure to ABSOLUTE MAXIMUM RATINGS conditions for extended periods may affect device reliability.
- Note 2. The data sheet limits are not guaranteed if the device is operated beyond the operating ratings.
- Note 3. Thermal performance assumes exposed pad is soldered (or equivalent) to the device's most negative potential (GND) on the PCB.
- Note 4. Due to the limited drive capability, use for input of the same package only.
- Note 5. The circuit is designed to meet the DC specifications shown in the above table after thermal equilibrium has been established.
- Note 6. V_{IH} (min.) not lower than 1.2V.

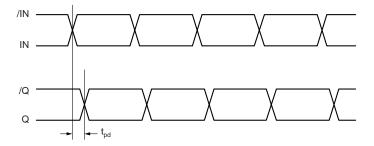
AC ELECTRICAL CHARACTERISTICS (Note 7)

 V_{CC} = 2.5V ±5% or 3.3V ±10%; T_A = -40°C to +85°C; R_L = 100 Ω across each output pair, or equivalent, unless otherwise stated.

| Symbol | Parameter | r | Condition | | Min | Тур | Max | Units |
|---------------------|-------------|---|---------------------------------|----------|-----|------|---------|----------------------|
| f _{MAX} | Maximum | Operating Frequency | | NRZ Data | | 10.7 | | Gbps |
| | | | V _{OUT} ≥ 200mV | Clock | 7 | 8 | | GHz |
| t _{pd} | Propagatio | on Delay | V _{IN} ≥ 100mV | | 100 | 170 | 250 | ps |
| t _{CHAN} | Channel-to | o-Channel Skew | Note 8 | | | 3 | 15 | ps |
| t _{SKEW} | Part-to-Par | rt Skew | Note 9 | | | | 100 | ps |
| t _{JITTER} | Data | Random Jitter (RJ) Deterministic Jitter (DJ) | Note 10 Note 11 | | | | 1 10 | ps(rms) ps(pk-pk) |
| | Clock | Cycle-to-Cycle Jitter Total Jitter (TJ) | Note 12 Note 13 | | | | 1 10 | ps(rms) ps(pk-pk) |
| t_r, t_f | Output Ris | e/Fall Time | 20% to 80% at full output swing | | 20 | 40 | 60 | ps |

- Note 7. High frequency AC electricals are guaranteed by design and characterization.
- Note 8. Skew is measured between outputs of the same bank under identical transitions.
- **Note 9.** Skew is defined for two parts with identical power supply voltages at the same temperature and with no skew of the edges at the respective inputs.
- Note 10. RJ is measured with a K28.7 comma detect character pattern, measured at 10.7Gbps and 2.5Gbps/3.2Gbps.
- Note 11. DJ is measured at 10.7Gbps and 2.5Gbps/3.2Gbps with both K28.5 and 2²³–1 PRBS pattern
- Note 12. Cycle-to-cycle jitter definition: The variation of periods between adjacent cycles, $T_n T_{n-1}$ where T is the time between rising edges of the output signal.
- Note 13. Total jitter definition: With an ideal clock input of frequency \leq f_{MAX} , no more than one output edge in 10^{12} output edges will deviate by more than the specified peak-to-peak jitter value.

TIMING DIAGRAM



SINGLE-ENDED AND DIFFERENTIAL SWINGS

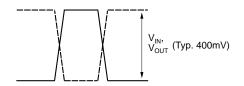


Figure 1a. Single-Ended Voltage Swing

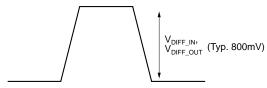
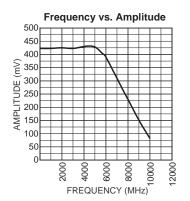
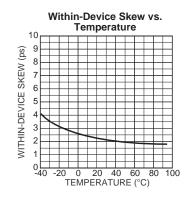


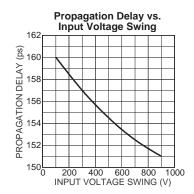
Figure 1b. Differential Voltage Swing

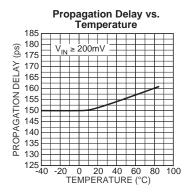
TYPICAL OPERATING CHARACTERISTICS

 V_{CC} = 3.3V, GND = 0, V_{IN} = 100mV, T_A = 25°C, unless otherwise stated.



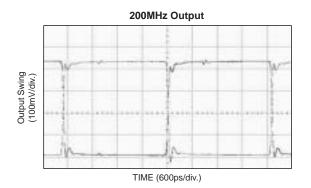


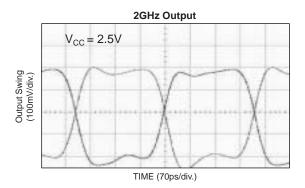


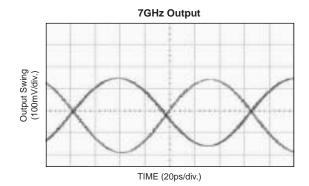


FUNCTIONAL CHARACTERISTICS

 V_{CC} = 2.5V, GND = 0, V_{IN} = 100mV, T_A = 25°C, unless otherwise stated.







INPUT STAGE

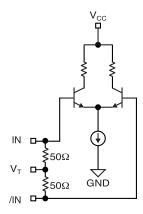
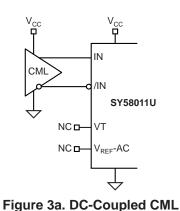


Figure 2. Simplified Differential **Input Buffer**

INPUT INTERFACE APPLICATIONS



Input Interface

(option: may connect V_T to V_{CC})

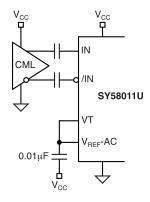


Figure 3b. AC-Coupled CML Input Interface

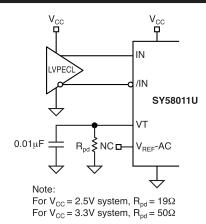
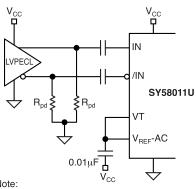


Figure 3c. LVPECL **Input Interface**



 $R_{pd} = 100\Omega$ for a 3.3V system $R_{pd} = 50\Omega$ for a 2.5V system

Figure 3d. AC-Coupled LVPECL Input Interface

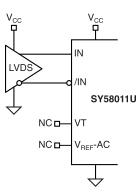


Figure 3e. LVDS **Input Interface**

CML OUTPUT TERMINATION

Figure 4 and Figure 5 illustrates how to terminate a CML output using both the AC-coupled and DC-coupled

configuration. All outputs of the SY58011 are 50Ω with a 16mA current source.

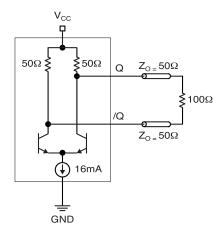


Figure 4. CML DC-Coupled Termination

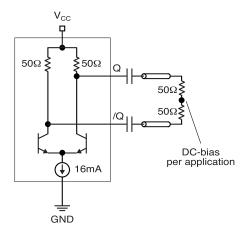
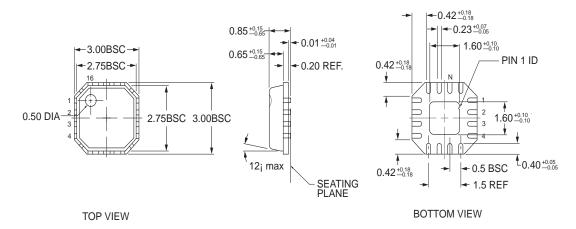


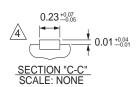
Figure 5. CML AC-Coupled Termination

RELATED MICREL PRODUCTS AND SUPPORT DOCUMENTATION

| Part Number | Function | Data Sheet Link |
|-------------|---|--|
| SY58011U | 7GHz, 1:2 CML Fanout Buffer/Translator with Internal I/O Termination | http://www.micrel.com/product-info/products/sy58011u.shtml |
| SY58012U | 5GHz, 1:2 LVPECL Fanout Buffer/Translator with Internal Input Termination | http://www.micrel.com/product-info/products/sy58012u.shtml |
| SY58013U | 6GHz, 1:2 Fanout Buffer/Translator with 400mV LVPECL Outputs and Internal Input Termination | http://www.micrel.com/product-info/products/sy58013u.shtml |
| | 16-MLF™ Manufacturing Guidelines Exposed Pad Application Note | www.amkor.com/products/notes_papers/MLF_AppNote_0902.pdf |
| | HBW Solutions | http://www.micrel.com/product-info/as/solutions.shtml |

16 LEAD *Micro*LeadFrame™ (MLF-16)





1. DIMENSIONS ARE IN mm.

2. DIE THICKNESS ALLOWABLE IS 0.305mm MAX.

3. PACKAGE WARPAGE MAX 0.05mm.

THIS DIMENSION APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.20mm AND 0.25mm FROM TIP.

Rev 02

5. APPLIES ONLY FOR TERMINALS

Package

EP- Exposed Pad

Die

CompSide Island

Heat Dissipation

Heavy Copper Plane

Vee

Heavy Copper Plane

PCB Thermal Consideration for 16-Pin MLF™ Package (Always solder, or equivalent, the exposed pad to the PCB)

Package Notes:

Note 1. Package meets Level 2 qualification.

Note 2. All parts are dry-packaged before shipment.

Note 3. Exposed pads must be soldered to a ground for proper thermal management.

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